



## Product Change Notification / NTDO-17SDDT634

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### Date:

07-Dec-2021

### Product Category:

32-bit Microcontrollers, Smart Energy Wireless Communications, Wireless Modules

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4529 Final Notice: Qualification of MTAI as an additional assembly site for selected AT86RF215, ATmega644/1284/2564RFR2 and ATSAM4Lx8xx device families available in 48L VQFN (7x7x0.9mm) package.

### Affected CPNs:

[NTDO-17SDDT634\\_Affected\\_CPN\\_12072021.pdf](#)

[NTDO-17SDDT634\\_Affected\\_CPN\\_12072021.csv](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of MTAI as an additional assembly site for selected AT86RF215, ATmega644/1284/2564RFR2 and ATSAM4Lx8xx device families available in 48L VQFN (7x7x0.9mm) package.

### Pre and Post Change Summary:

*For AT86RF215 device family currently assembled in ASE:*

	Pre Change	Post Change
<b>Assembly Site</b>	ASE Inc. (ASE)	Microchip Technology Thailand (HQ) (MTAI)
<b>Wire material</b>	PdCu	Au
<b>Die attach material</b>	EN-4900F	3280
<b>Molding compound material</b>	G631H	G700LTD
<b>MSL information</b>	MSL 3	MSL 1
<b>Lead frame material</b>	C194	C194
<b>DAP Surface Prep</b>	Ag Ring plating	Bare Cu
<b>Lead frame plating finish</b>	Matte tin	Matte tin
<b>Lead frame lead-lock</b>	No	Yes
	See Pre and Post Change attachment for lead frame comparison	

**For AT86RF215, ATmega644/1284/2564RFR and ATSAM4Lx8xx device families currently assembled in ASE and MMT:**

	Pre Change		Post Change		
<b>Assembly Site</b>	ASE Inc. (ASE)	Microchip Technology Thailand (Branch) (MMT)	ASE Inc. (ASE)	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (HQ) (MTAI)
<b>Wire material</b>	PdCu	Au	PdCu	Au	Au
<b>Die attach material</b>	EN-4900F	3280	EN-4900F	3280	3280
<b>Molding compound material</b>	G631H	G700LTD	G631H	G700LTD	G700LTD
<b>MSL information</b>	MSL 3	MSL 1	MSL 3	MSL 1	MSL 1

<b>Lead frame material</b>	C194	C194	C194	C194	C194
<b>DAP Surface Prep</b>	Ag Ring plating	Bare Cu	Ag Ring plating	Bare Cu	Bare Cu
<b>Lead frame plating finish</b>	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin
<b>Lead frame lead-lock</b>	No	Yes	No	Yes	Yes
See Pre and Post Change attachment for lead frame comparison					

***For ATmega2564RFR device families currently assembled in ATP7 and MMT:***

	Pre Change		Post Change		
<b>Assembly Site</b>	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Microchip Technology Thailand (Branch) (MMT)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (HQ) (MTAI)
<b>Wire material</b>	AuPd	Au	AuPd	Au	Au
<b>Die attach material</b>	AMK-06	3280	AMK-06	3280	3280
<b>Molding compound material</b>	G700Y	G700LTD	G700Y	G700LTD	G700LTD
<b>MSL information</b>	MSL 3	MSL 1	MSL 3	MSL 1	MSL 1
<b>Lead frame material</b>	C194	C194	C194	C194	C194
<b>DAP Surface Prep</b>	Bare Cu	Bare Cu	Bare Cu	Bare Cu	Bare Cu
<b>Lead frame plating finish</b>	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin
<b>Lead frame lead-lock</b>	No	Yes	No	Yes	Yes

See Pre and Post Change attachment for lead frame comparison

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**December 29, 2021 (date code: 2153)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	July 2021					>	December 2021				
Workweek	27	28	29	30	31		49	50	51	52	53
Initial PCN Issue Date				x							
Qual Report Availability								x			
Final PCN Issue Date								x			
Estimated Implementation Date											x

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**July 2, 2021: Issued initial notification.

December 7, 2021: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on December 29, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the

material content of the applicable products.

## **Attachments:**

[PCN\\_NTDO-17SDDT634 Qual Report.pdf](#)

[PCN\\_NTDO-17SDDT634\\_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

AT86RF215-ZU  
AT86RF215IQ-ZU  
AT86RF215-ZU-004  
AT86RF215M-ZU  
AT86RF215-ZUR  
AT86RF215-ZUR004  
AT86RF215M-ZUR  
ATMEGA2564RFR2-ZF  
ATMEGA2564RFR2-ZFR  
ATSAM4LS8AA-MU  
ATSAM4LC8AA-MU  
ATSAM4LS8AA-MUR  
ATSAM4LC8AA-MUR  
ATMEGA1284RFR2-ZF  
ATMEGA644RFR2-ZF  
ATMEGA2564RFR2-ZU  
ATMEGA1284RFR2-ZU  
ATMEGA644RFR2-ZU  
ATMEGA644RFR2-ZUR  
ATMEGA2564RFR2-ZUR  
ATMEGA1284RFR2-ZUR  
ATMEGA1284RFR2-ZFR  
ATMEGA644RFR2-ZFR  
ATMEGA2564RFR2-ZFRP01